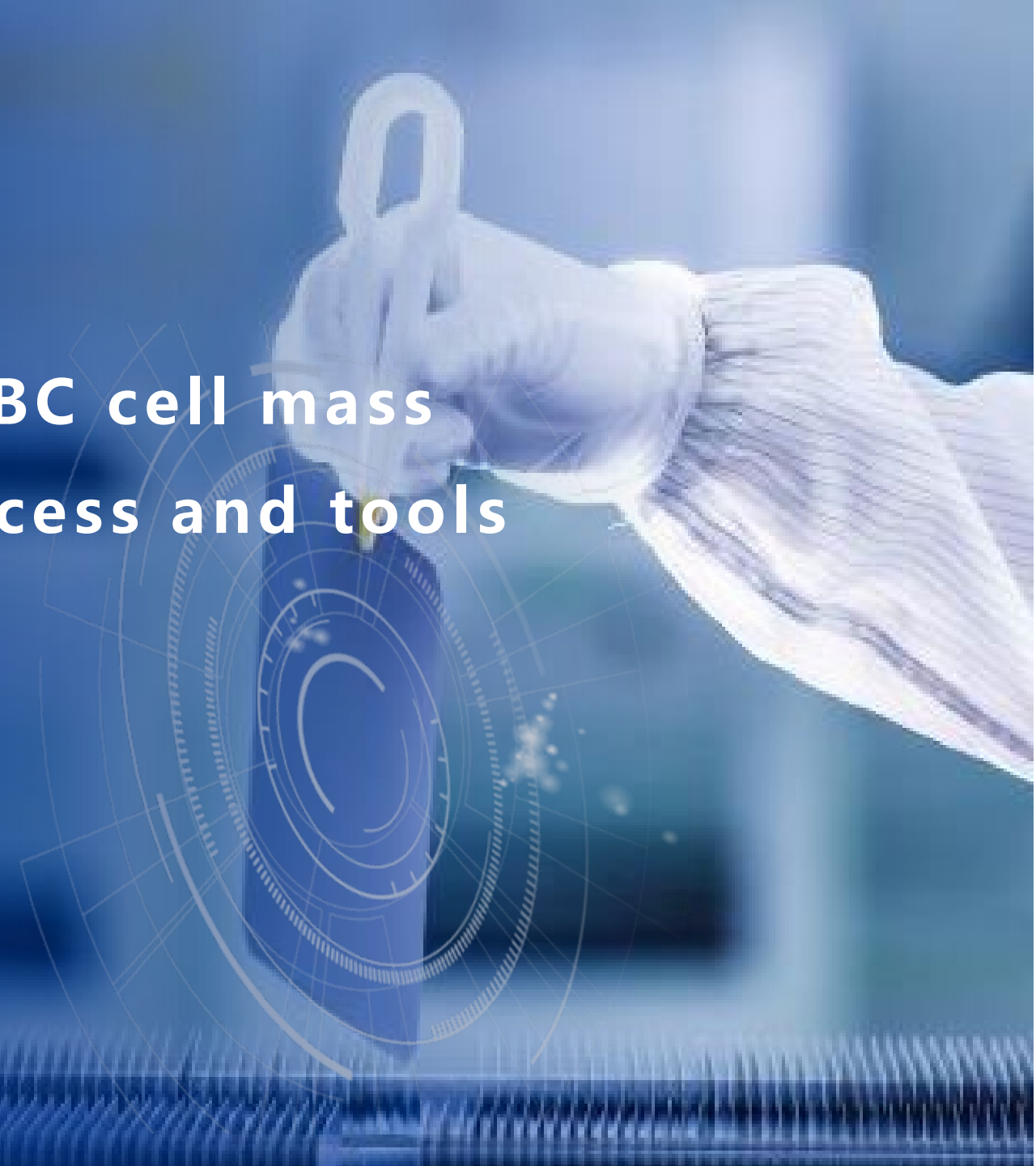


Several key blocks for TBC cell mass production: half cut process and tools

Xiajie Meng

2024.12.04



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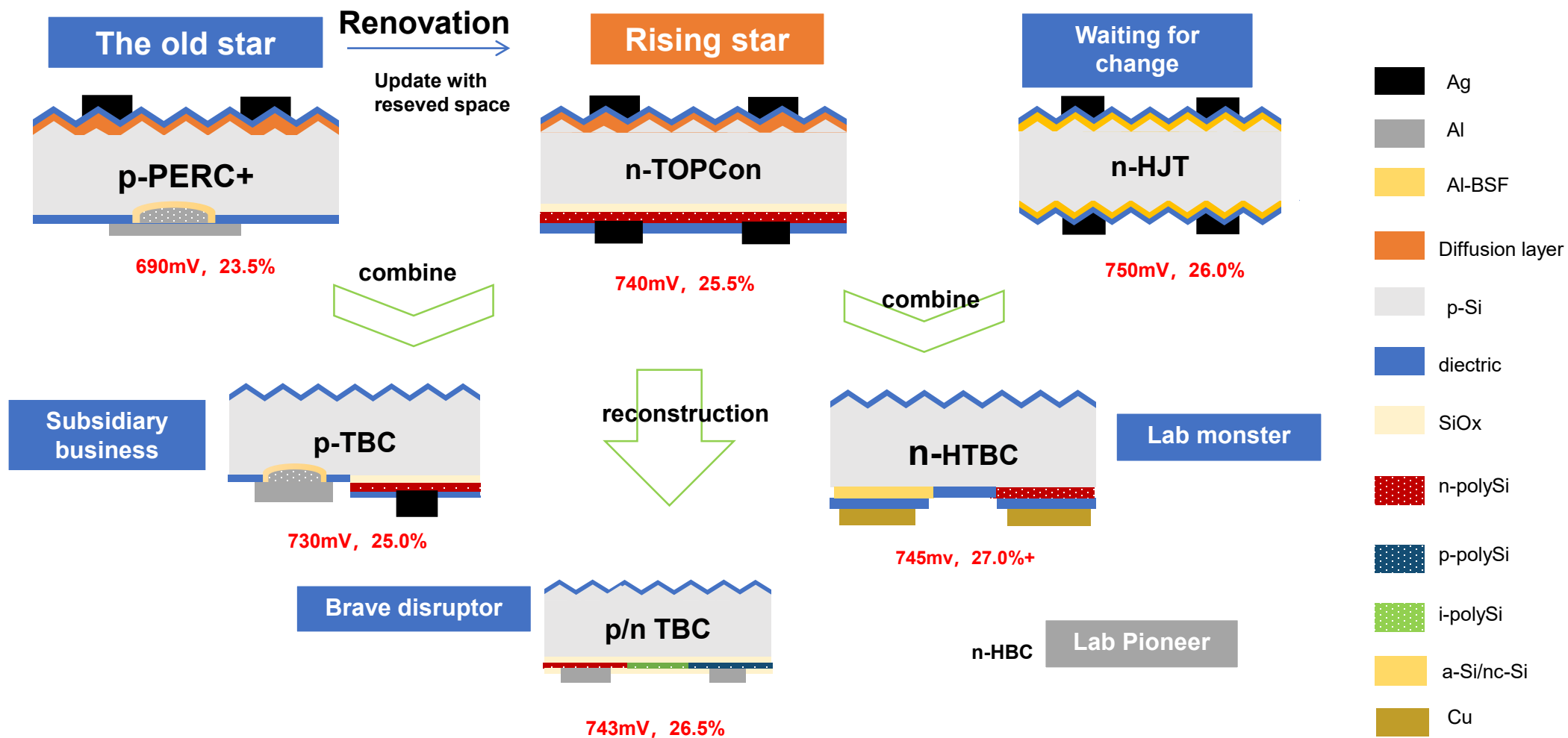
01 Industrial c-Si solar cell structure

02 Efficiency paradox

03 Blocks for cheap TBC

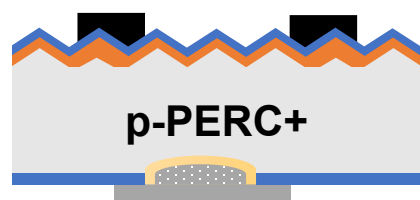
04 Outlook

TOPCon became mainstream in 2024

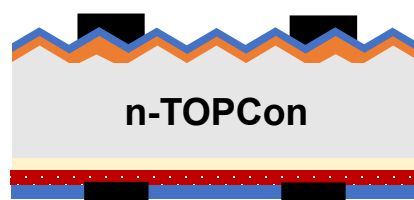


Efficiency pradox, struggle for BC future

Solar Cell Efficiency Tables (Version 65) 21/10/2024



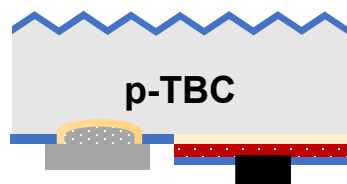
694mV, **24.0%**, 07/2019



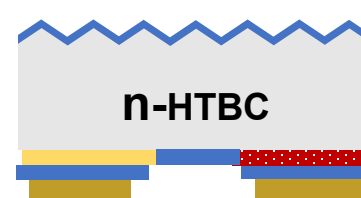
744mV, **26.58%**,
11/2024



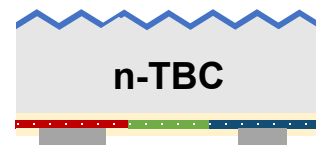
751.4mV, **26.8%**,
10/2022















733mV, **25.5%**
lab data



745.6mV, **27.4%**,
09/2024

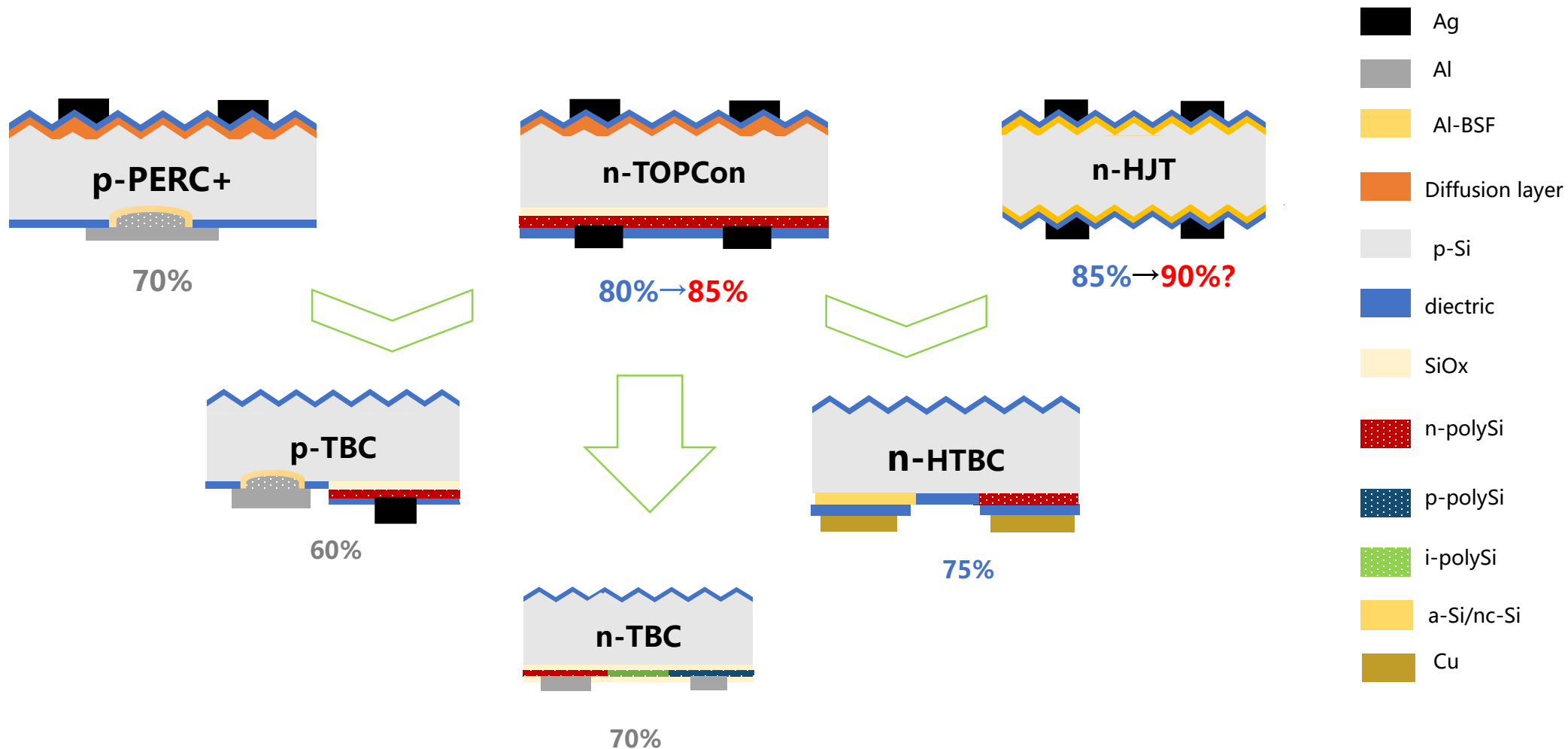


744.7mV, **27.0%**
08/2024

-  Ag
-  Al
-  Al-BSF
-  Diffusion layer
-  p-Si
-  dielectric
-  SiOx
-  n-polySi
-  p-polySi
-  i-polySi
-  a-Si/nc-Si
-  Cu

Block 1, bifaciality

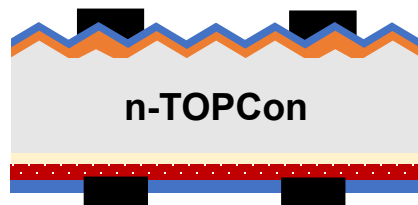
Customer doesn't pay for bifaciality, but utility choose the higher and the more reliable





Block 2, diligent rising star

TOPCon inline innovation is moving fast



25.5%
80% 2024

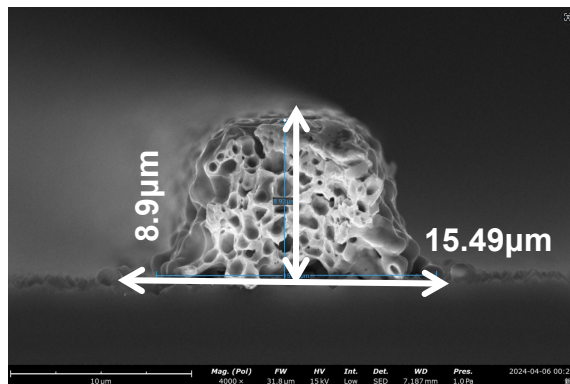
The rising star will get another 0.4% EFF next year.

Inline innovation based on screen shift or single tool integration are easy to be applied.

TOPCon will get extraordinary bifaciality for utility market.

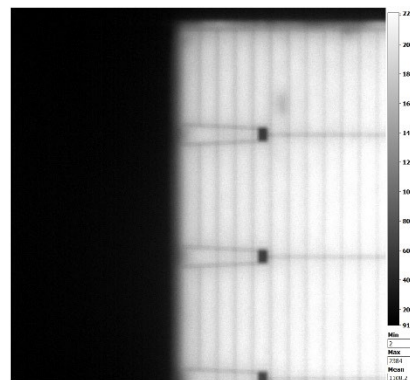
Stencil printing

- 0.15% EFF gain
- silver saving as low as to **8 mg/w**



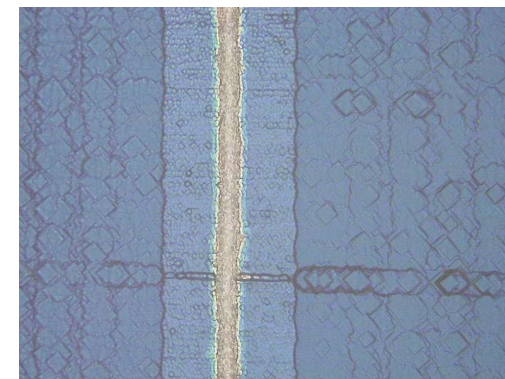
Edge passivation

- Pickup 0.15% EFF laser cleavage loss
- Easy **inline integration**



Rear Polyfinger

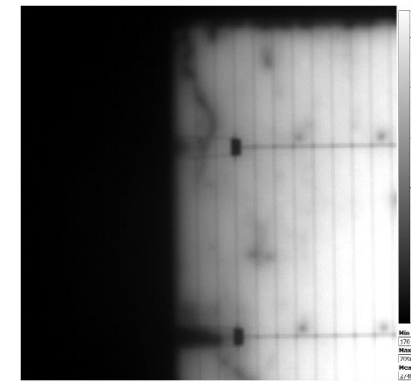
- 0.15% EFF gain
- **85% bifaciality** for utility market



Block 3, EFF of half cut loss

TBC/HTBC mass production from half cut raw wafar

- PERC Shingle, HJT and n-TBC laser cut loss are TOP 3.
- **0.35% EFF half cut loss** for n-TBC is equal to **7W** for module at 2278x1134 mm size.
- HJT process in industry is already half cut.
- TBC cells are difficult to stack together for edge passivation.

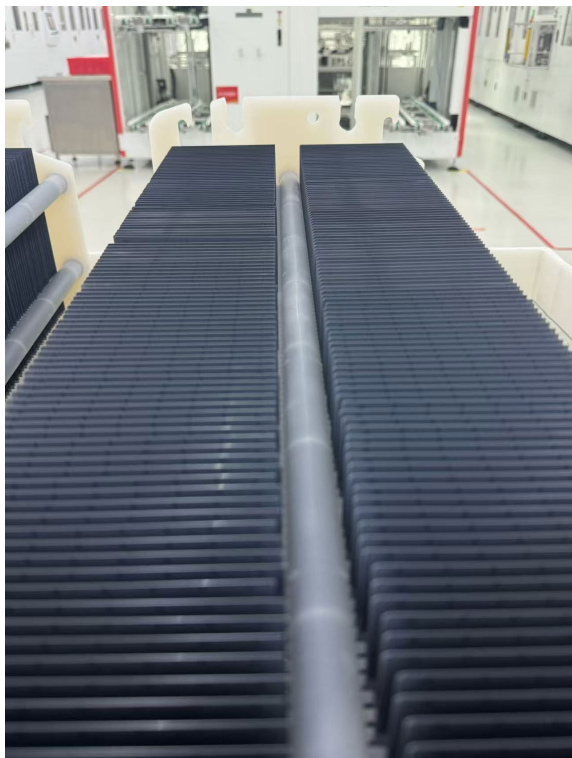


Edge recombination because of laser thermal half cut
 PL pic, HJT 1sun

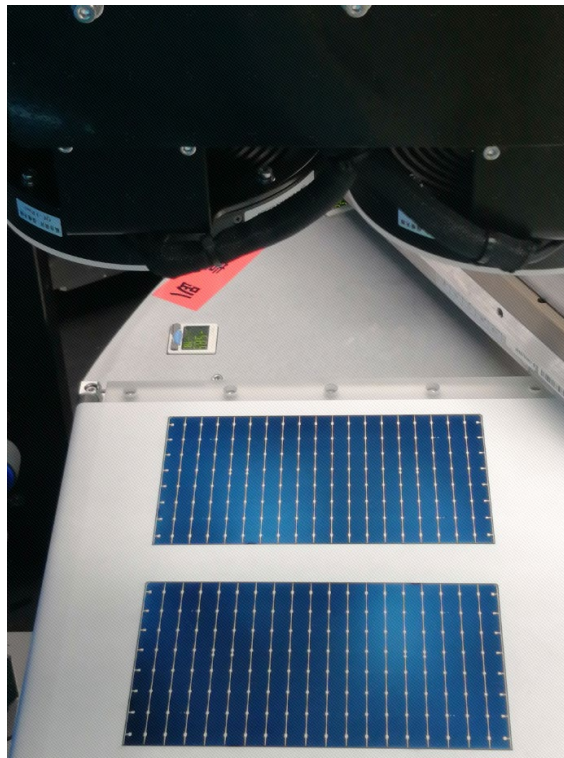
Cell	Type	Class Bin	Cut loss						
			$\Delta\text{Eff} (\%)$	$J_{sc} (\text{mA/cm}^2)$	$\Delta V_{oc} (\text{mV})$	$\Delta\text{FF} (\%)$	$\Delta\text{PFF} (\%)$	$\Delta J_{02} (\text{nA/cm}^2)$	
HJT	156	25.0%	-0.58 TOP①	-0.03	-2.06	-1.68	-1.78	2.63	
PERC	182	23.0%	-0.17	-0.08	-0.62	-0.37	-0.33	1.14	
	210-Shingle 6 cut	22.8%	-0.47 TOP②	0.01	-0.62	-1.61	/	/	
TOPCon	182	24.6%	-0.21	0.00	-0.42	-0.67	-0.56	1.53	
p-TBC	182	25.0%	-0.20	-0.22	-0.42	-0.20	-0.22	0.26	
n-TBC	182	26.7%	-0.35 TOP③	-0.10	-1.18	-0.77	-0.68	0.80	

Solution trial, half cut TBC mass production

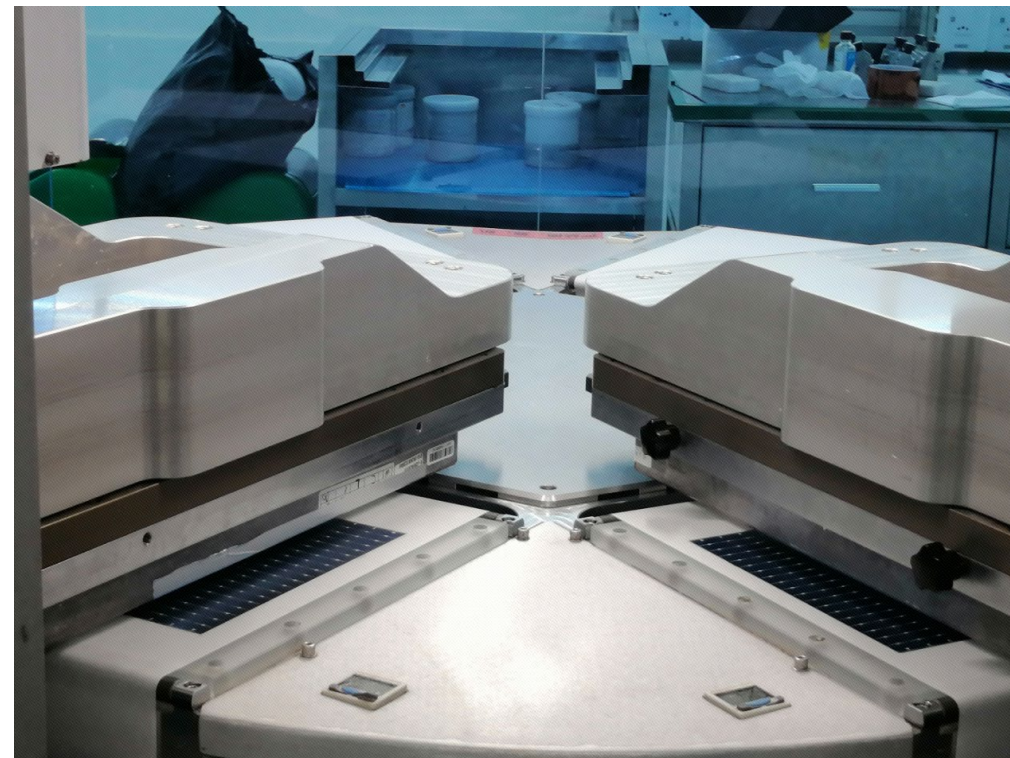
Automation Carrier
Two rows in one



One camera for two cell alignment



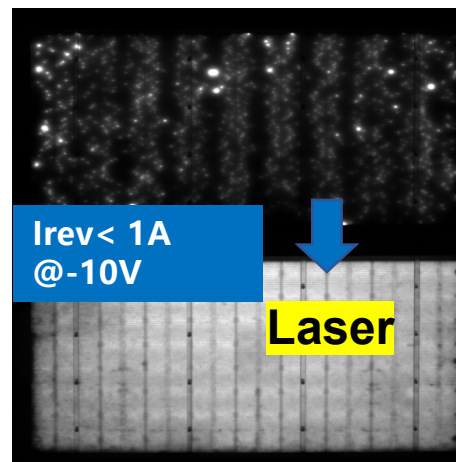
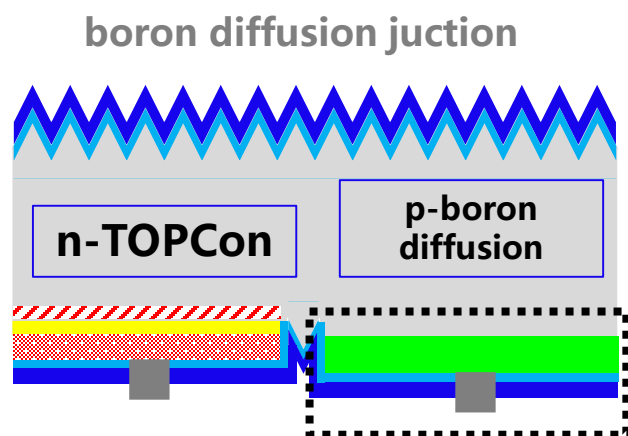
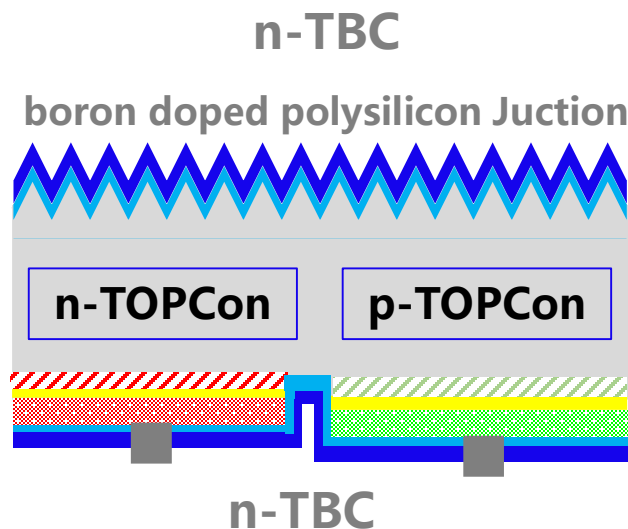
Hexagon half cut cell printer



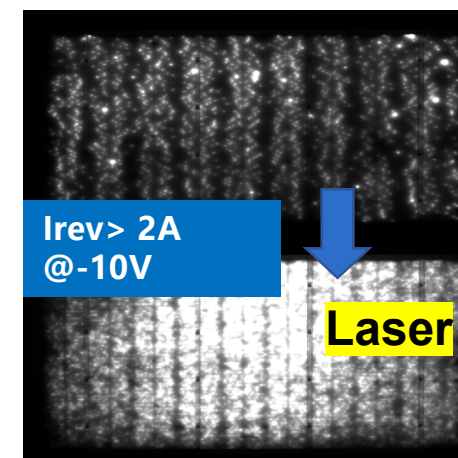
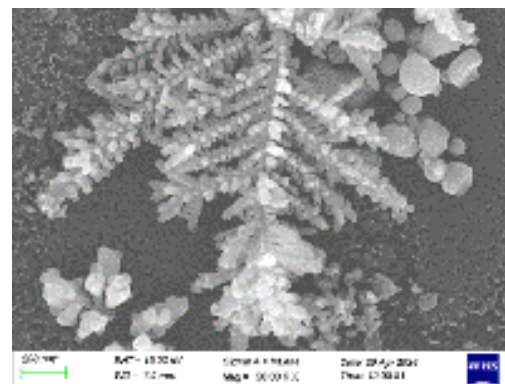
Block 4, Simplified TBC based on boron diffusion

Simplified boron diffusion junction is hard to form good contact

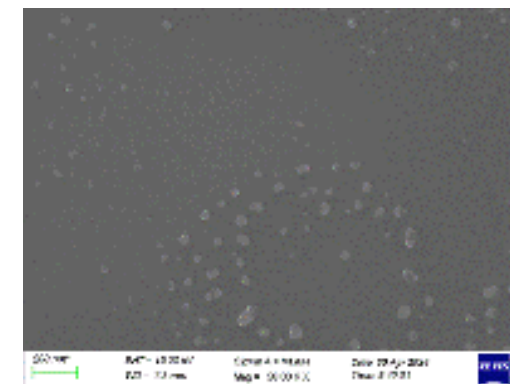
It is hard to create enough electrons required for silver redox because of low breakdown voltage



Standard: $\rho_{c,p} \sim 1\text{m}\Omega\cdot\text{cm}^2$
Fire → LED furnace hydrogenation



Laser induced Firing: $\rho_{c,p} \sim 10\text{m}\Omega\cdot\text{cm}^2$
Fire → Laser induced contact formation



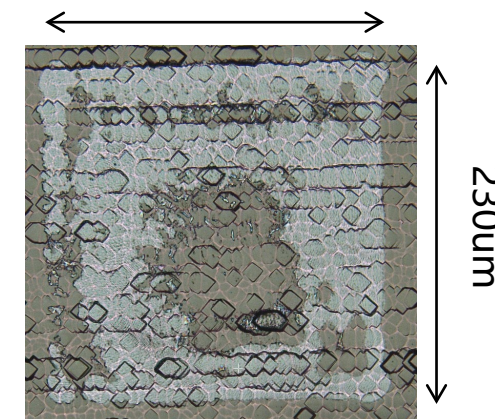
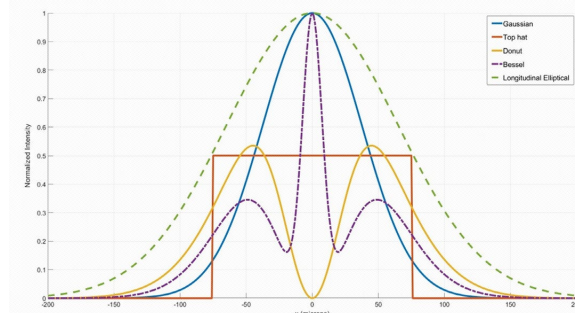
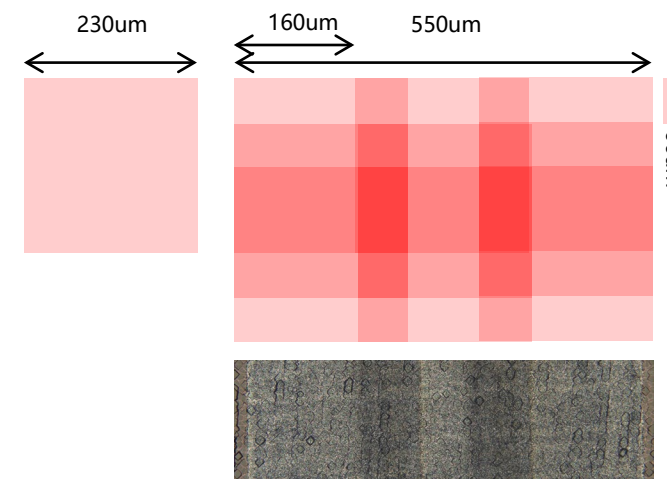
Block 5, Expensive Laser

- Pico second laser is required to open PSG or BSG for patterning.
- Ultra fast laser gaussian beam is shaped by DOE.
- Single spot of laser is shaped to “Donut”.
- 50% overlap is applied for complete opening.

The trouble is TBC requires over 100% area patterning.

Over 100W high power laser is still expensive for solar.

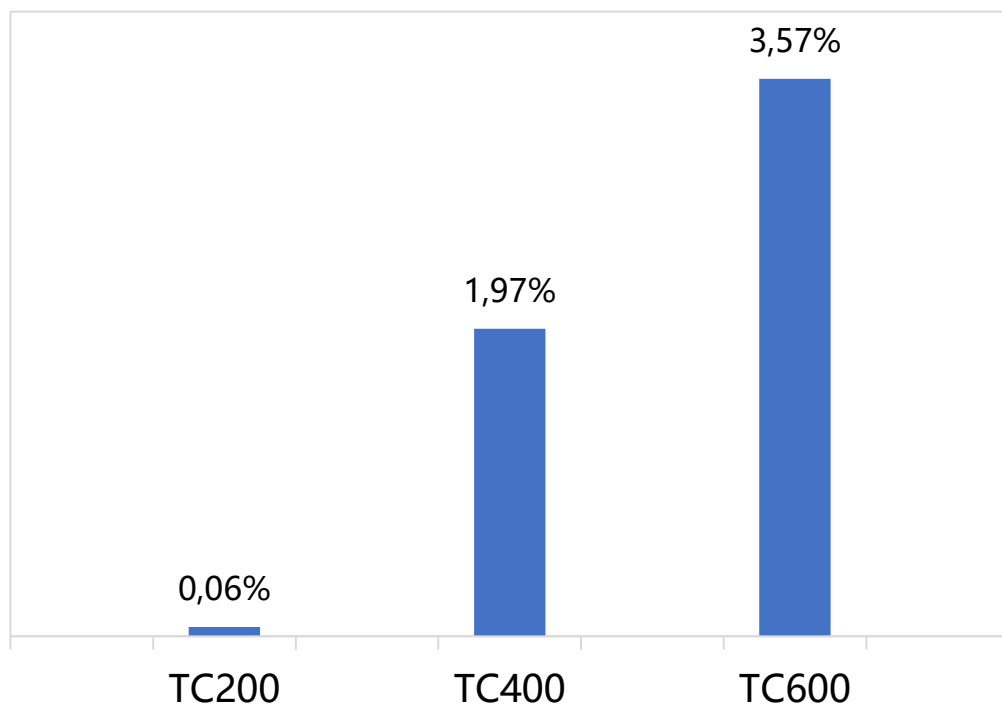
Moreover, the yield is too low for single laser head.



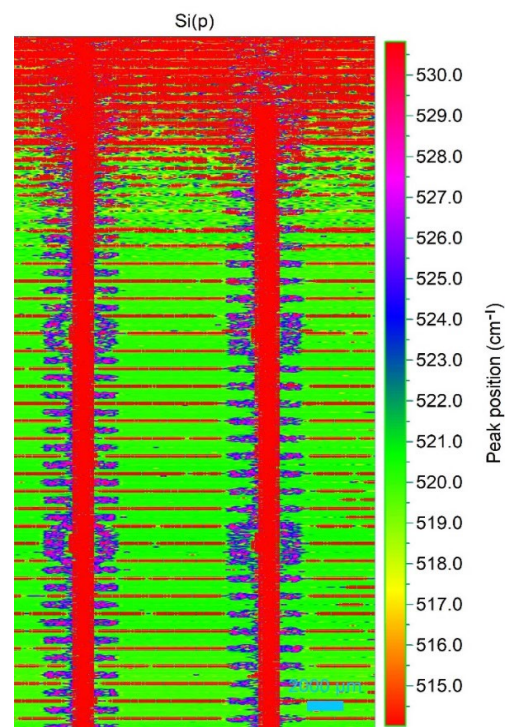
Block 6, thermal cycle

The tension between ribbon and Ag pad of back contact module is located at the cell edge, as shown in the Raman image. After thermal cycle, delamination grows.

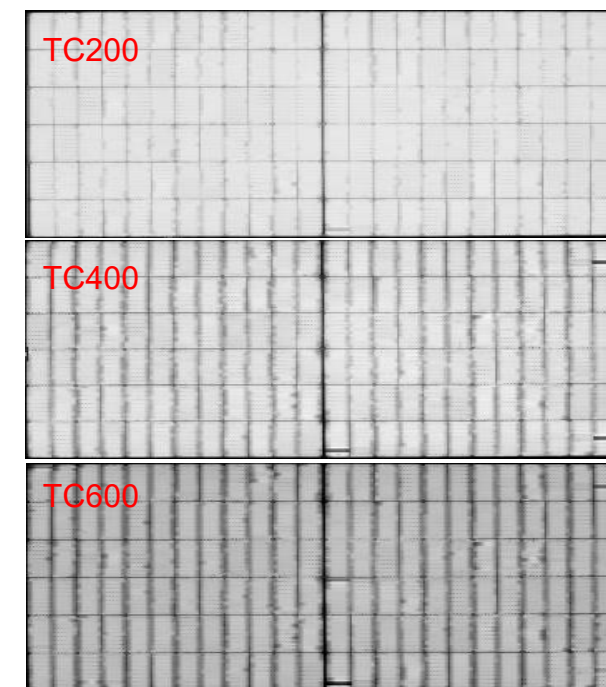
Module efficiency loss after thermal cycle



Raman image of silicon



Electroluminescence image



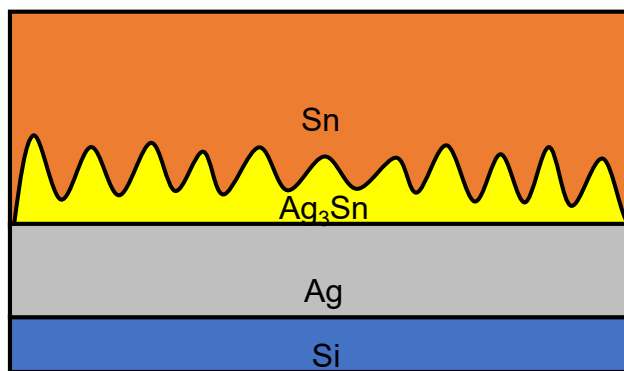
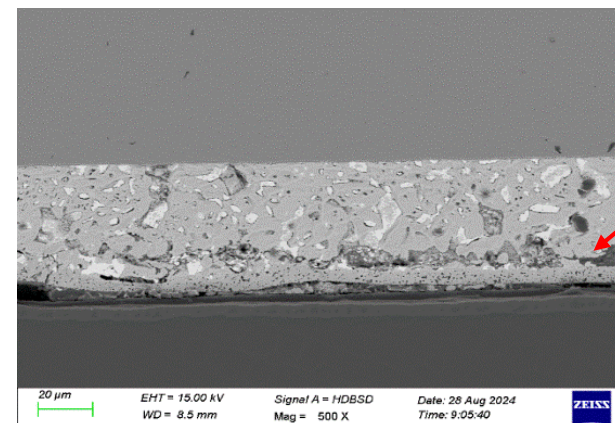
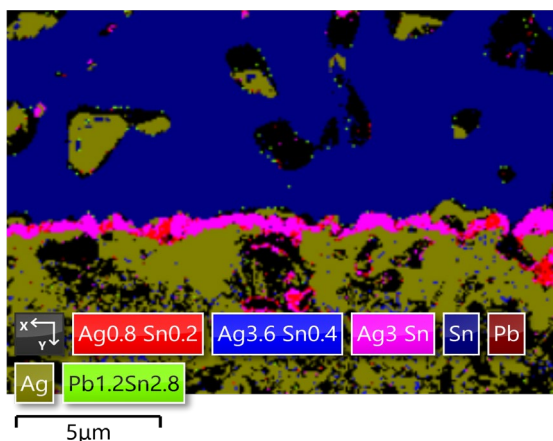
Block 7, Ag consumption in solder joint

Sn diffusion to Ag attacks solder joint. Delamination is often discovered after damp heat as well.

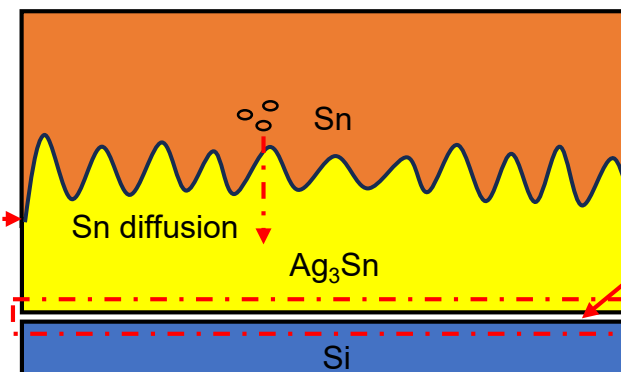
Zero busbar BC module design is also restricted by edge sold pad area.

TBC back contact solder joint is over **3mg/W**. nearly 40% of TOPCon Ag paste

Silver cost for BC is nearly 1.5~2 time as TOPCon. Is copper the solution? **Plating or Copper Paste?**



Heat



Conclusion

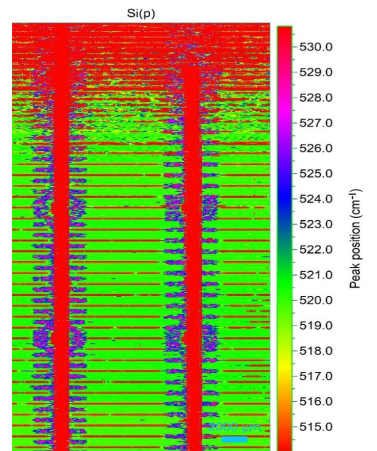
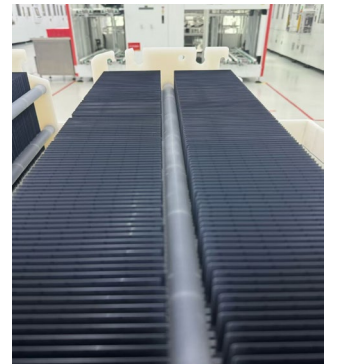
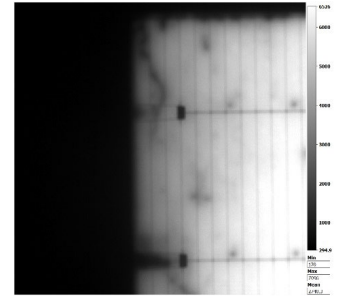
Back contact cell reaches top 3 in solar efficiency table in practical.

There are still several blocks for TBC cell mass production:

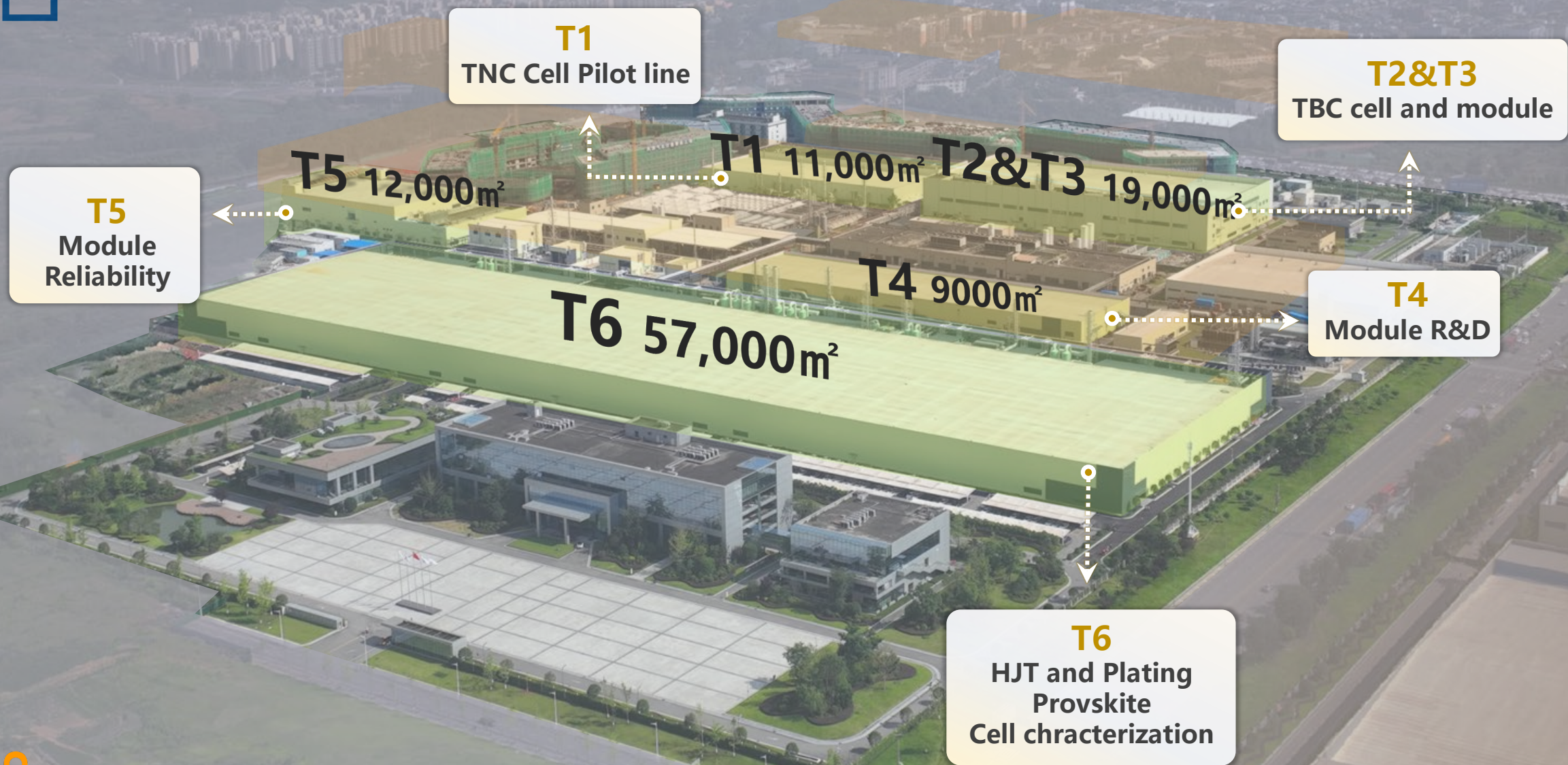
1. Bifacial limit,
2. Deligent rising star TOPCon in-line upgrade rapidly,
3. EFF of half cut loss,
4. Simplified TBC structure with boron diffusion junction but not easy in experiment trial,
5. Expensive laser and low yield,
6. Thermal cycle induced delamination,
7. Ag consumption in solder joint.

TBC and HTBC will be one of the future.

Half cut and tools are one possible solution trial for future mass production



Tongwei R&D



Thanks!

